

**IN THE CLAIMS:**

Please amend the claims as follows:

1. (Cancelled)

2. (Cancelled)

3. (Withdrawn)      A method of cleaning a component for a film forming equipment, characterized by that after a thin film has been formed on the substrate by the film forming equipment, the component as claimed in claim 1 or 2 is dipped in a cleaning fluid to remove an deposited film consisting of the film forming material from the component.

4. (Withdrawn)      The method as claimed in claim 3, characterized by that a positive electric field is applied to the matrix metal material of said component dipped in the cleaning fluid.

5. (Cancelled)

6. (Currently Amended)      A component in of a film forming equipment for forming a thin film on a substrate, the component having:

a matrix material;

a first means<sub>1</sub> on said the matrix material<sub>1</sub> for forming a first local cell, when exposed to a cleaning liquid, with the matrix material so, the first means being of such a

character that a first local current flows from the matrix material ~~thereby advancing to~~  
advance dissolution of the first means at an interface between the first means and the  
matrix material and ~~allowing to allow~~ the removal of a film layer of the thin film from the  
matrix material; and

a second means, on said ~~the~~ first means, for forming a second local cell, when  
exposed to a cleaning liquid, ~~so~~ the second means being of such a character that a  
second local current flows from the second means ~~thereby advancing to advance~~  
dissolution of the first means at an interface between the first means and the second  
means and ~~allowing to allow~~ the removal of the film layer of the thin film from the matrix  
material.